

**FOR IMMEDIATE RELEASE**

## YINCAE to Showcase Breakthrough at IMAPS 2026

**(Menands, NY)** July 29 – YINCAE Advanced Materials will showcase its latest innovations in advanced semiconductor packaging materials at the 59th International Symposium on Microelectronics, on September 28–October 1, 2026, Boston, Massachusetts.

At IMAPS 2026, YINCAE will present a comprehensive portfolio of high-performance materials developed for artificial intelligence (AI), high-performance computing (HPC), data centers, silicon photonics, optical interconnects, power electronics, and quantum computing.

Featured technologies include UV-curable Low-K and High-K encapsulation and underfill materials designed to improve electrical performance while delivering outstanding package reliability. The Low-K materials minimize dielectric loss and signal attenuation for high-speed computing applications, while the High-K materials enable advanced electronic packaging requiring enhanced electrical performance. These materials have demonstrated excellent environmental durability, successfully passing Pressure Cooker Test (PCT) qualification.

YINCAE will also introduce its latest thermal underfills and capillary underfills, which have demonstrated exceptional reliability by withstanding 10x260°C lead-free reflow cycles without flux residue cleaning, maintaining excellent adhesion, mechanical strength, and electrical performance throughout the assembly process.

Visit YINCAE booth # 408 at IMAPS 2026 to learn more details or to schedule a meeting during IMAPS 2026, please visit [www.yincae.com](http://www.yincae.com)

### **About YINCAE Advanced Materials**

YINCAE Advanced Materials develops innovative adhesives, encapsulants, underfills, die attach adhesives, thermal interface materials, and advanced packaging solutions for the semiconductor, optoelectronics, telecommunications, automotive, aerospace, medical, and industrial electronics industries. YINCAE's technologies help customers achieve higher performance, greater reliability, and more efficient manufacturing for next-generation electronic devices.